



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2814
Examiner: Phat X. Cao

In re PATENT APPLICATION of:

Applicant(s): Nobuhisa KUMAMOTO et al.

Serial No.: 10/767,439

Filing date: January 30, 2004

For: PROCESS OF PRODUCING
SEMICONDUCTOR CHIP WITH SURFACE
INTERCONNECTION AT BUMP (as amended)

Atty. ref.: AI 318 D1

**AMENDMENT
AFTER
FINAL REJECTION**

September 10, 2007

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is responsive to the Office Action of June 11, 2007, the period for reply to which has been set to expire on September 11, 2007.

A fee of \$None is also being submitted concurrently. Should this remittance be accidentally missing, however, or should any additional fees be needed, the Director may charge such fees to our Deposit Account number 18-0002.

Please amend above-identified application as specified on the following pages, and then reconsider the application in view of the Remarks that are presented thereafter.